

FIG. 1A

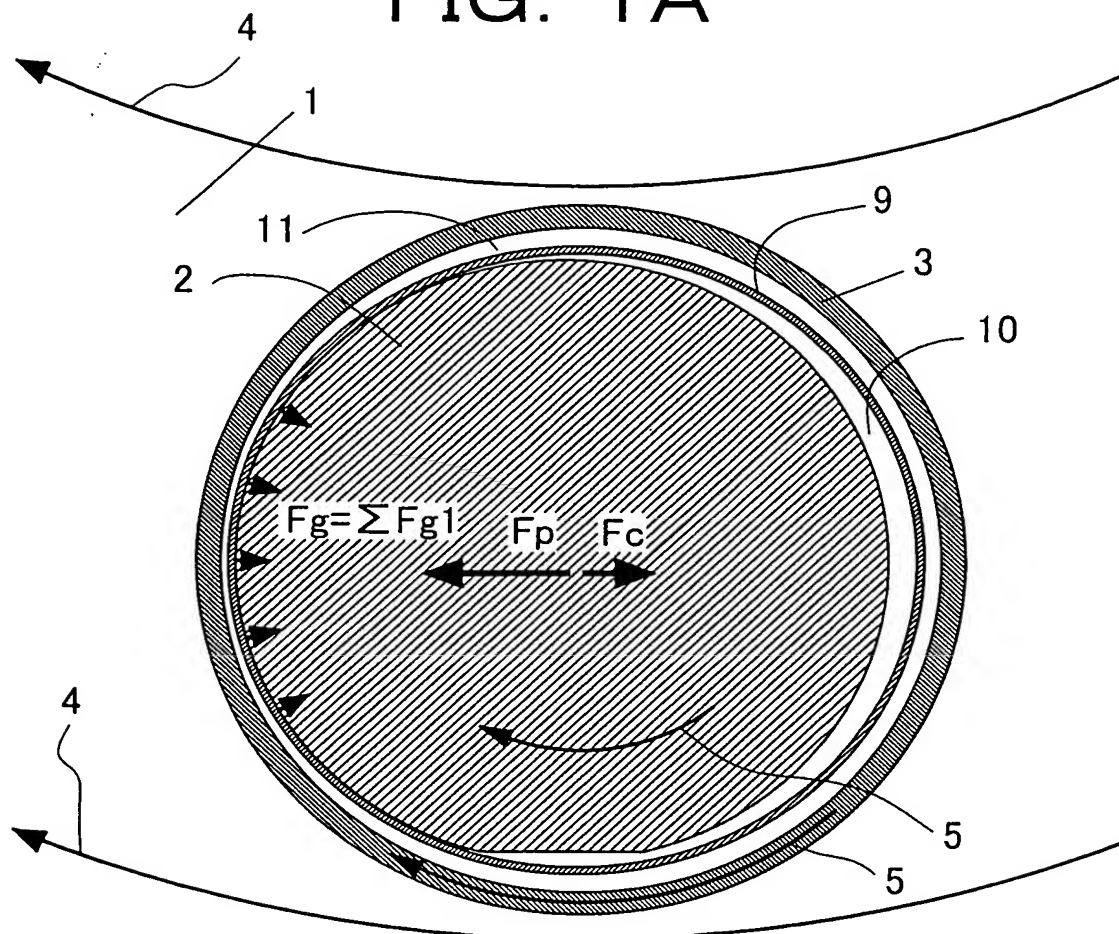


FIG. 1B

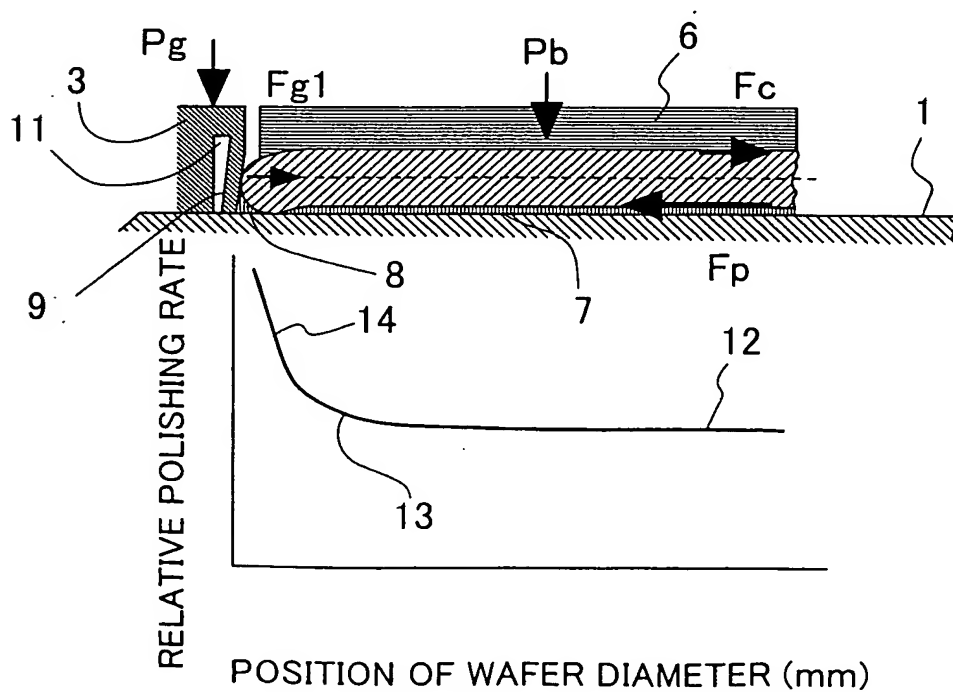


FIG. 2A

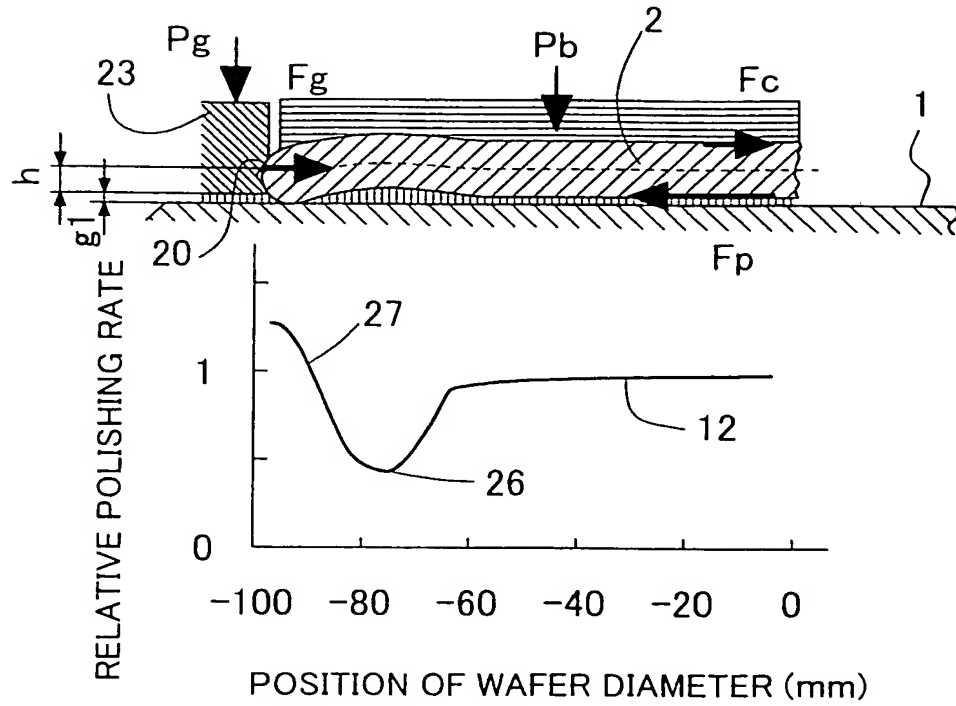


FIG. 2B

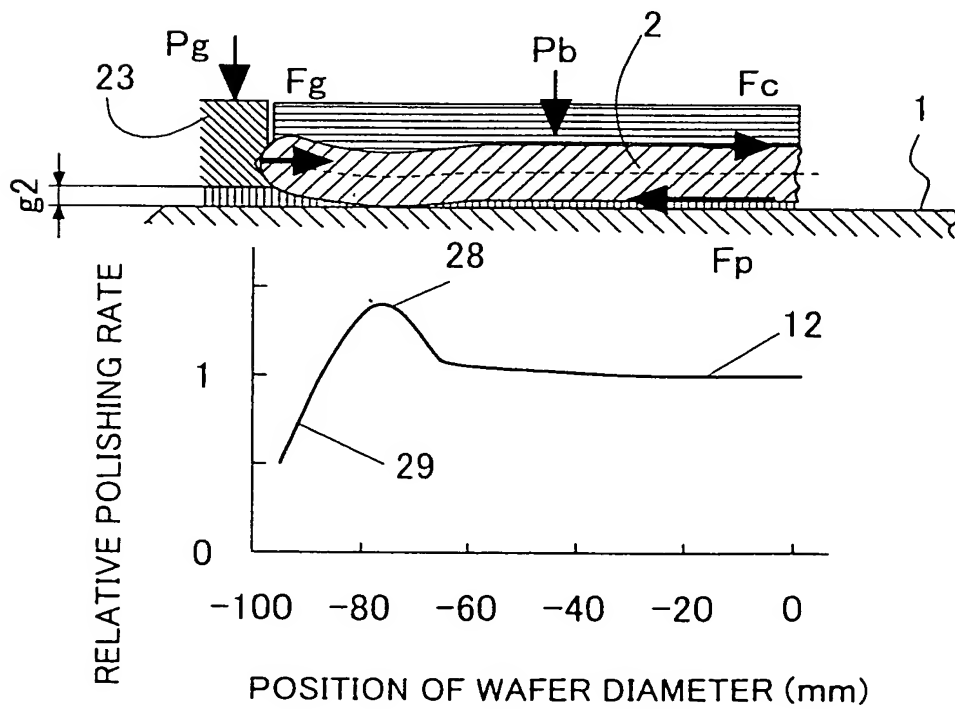


FIG. 3A

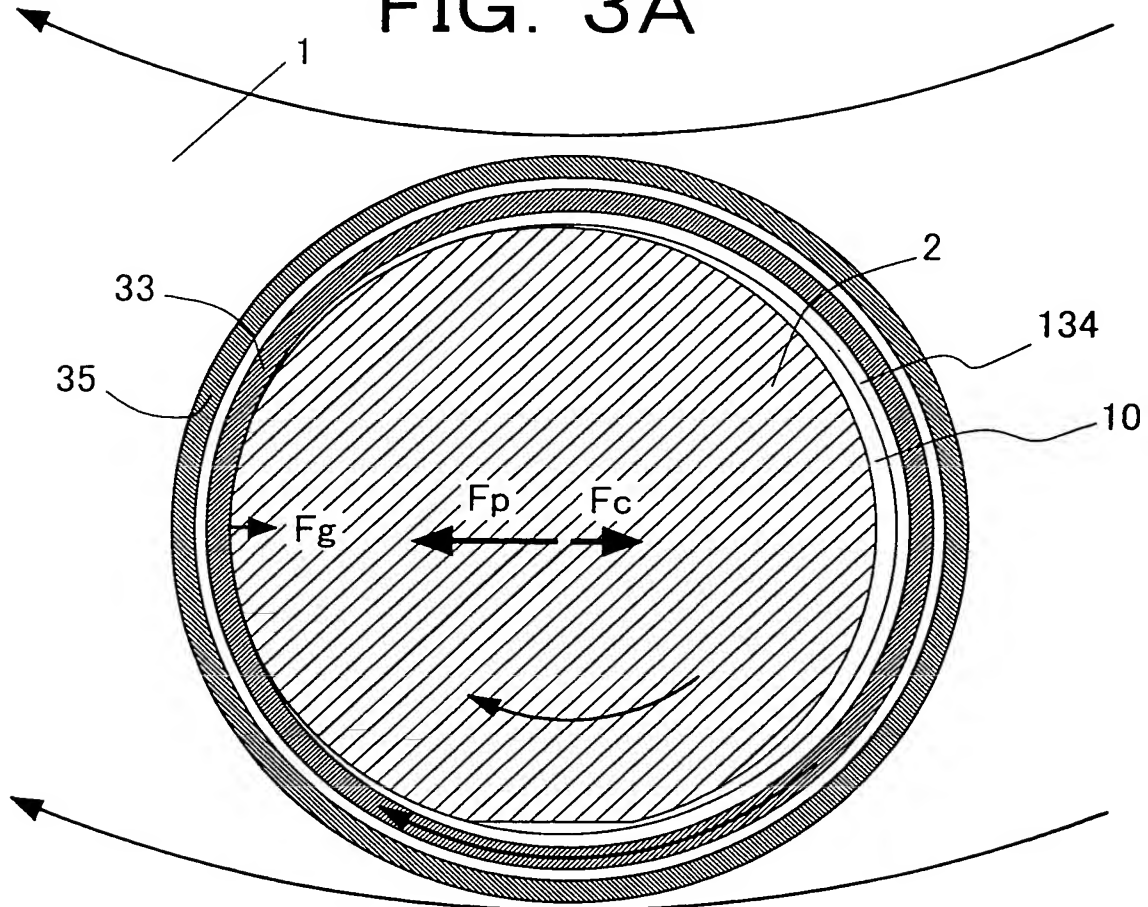


FIG. 3B

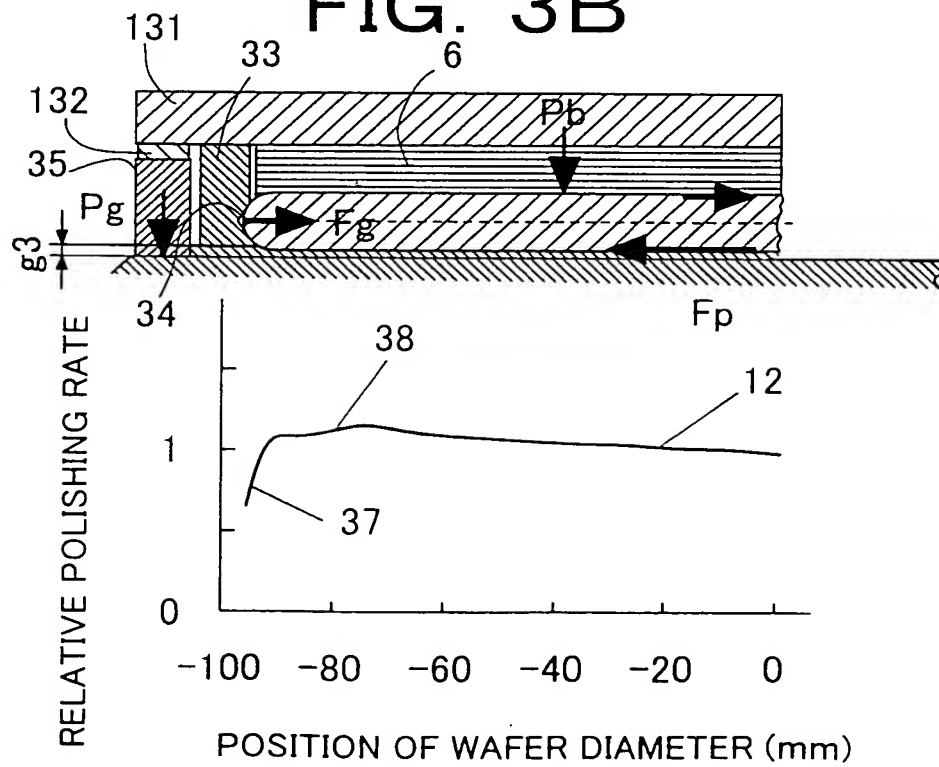


Figure 1 consists of two parts. The top part is a schematic diagram of a polishing apparatus. It shows a cross-section of a wafer (1) being polished by a polishing head (2). The head includes a polishing pad (6) and a backing plate (43). A pressure P_g is applied to the pad, and a pressure P_b is applied to the wafer. Forces F_{g1} and F_c are indicated. A hatched region (35) is shown on the left, and a hatched region (44) is shown on the right. The bottom part is a graph showing the relative polishing rate (Y-axis, 0 to 1) versus the position of wafer diameter (X-axis, -100 to 0 mm). The graph shows a curve (48) that is relatively flat at a rate of 1.0, with a small dip (49) around -80 mm. A label (12) points to the curve.

FIG. 5A

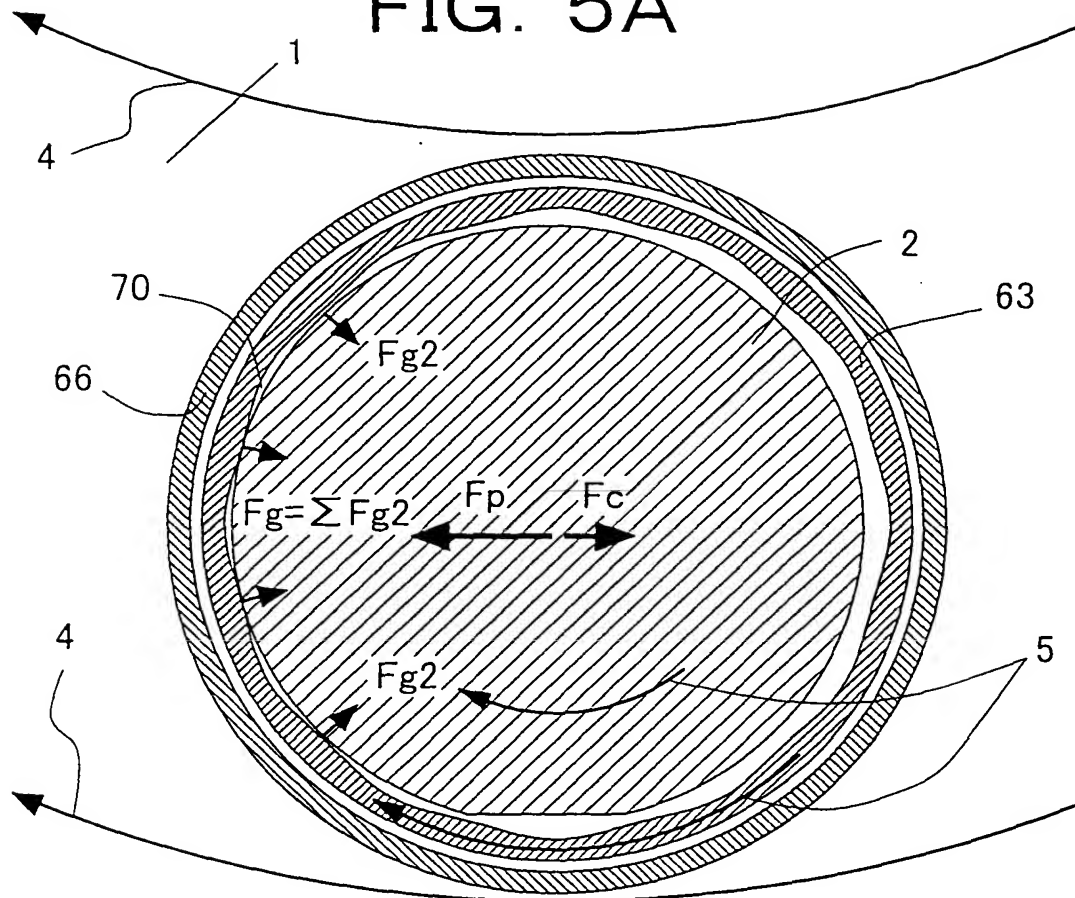


FIG. 5B

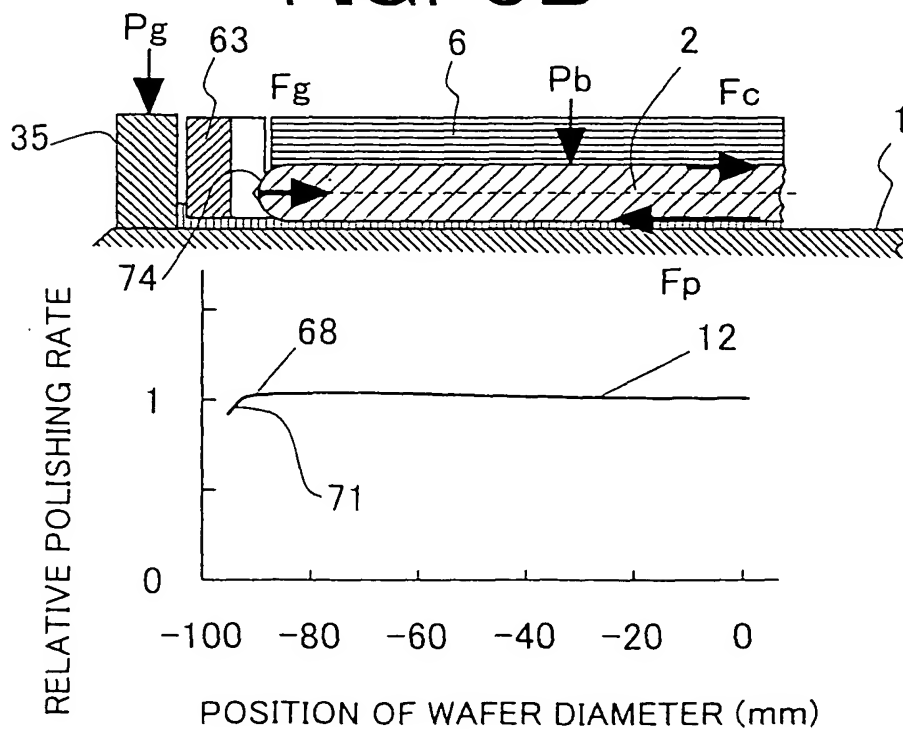


FIG. 6A

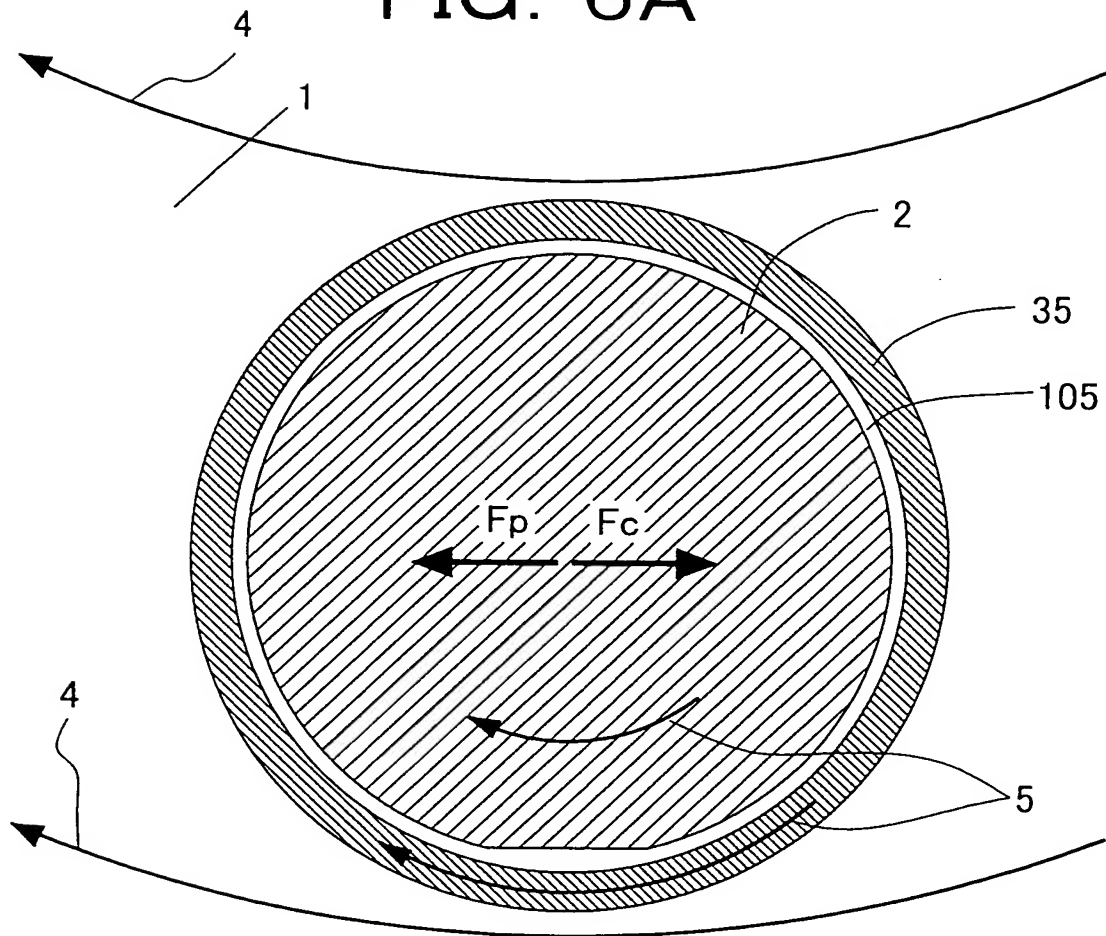


FIG. 6B

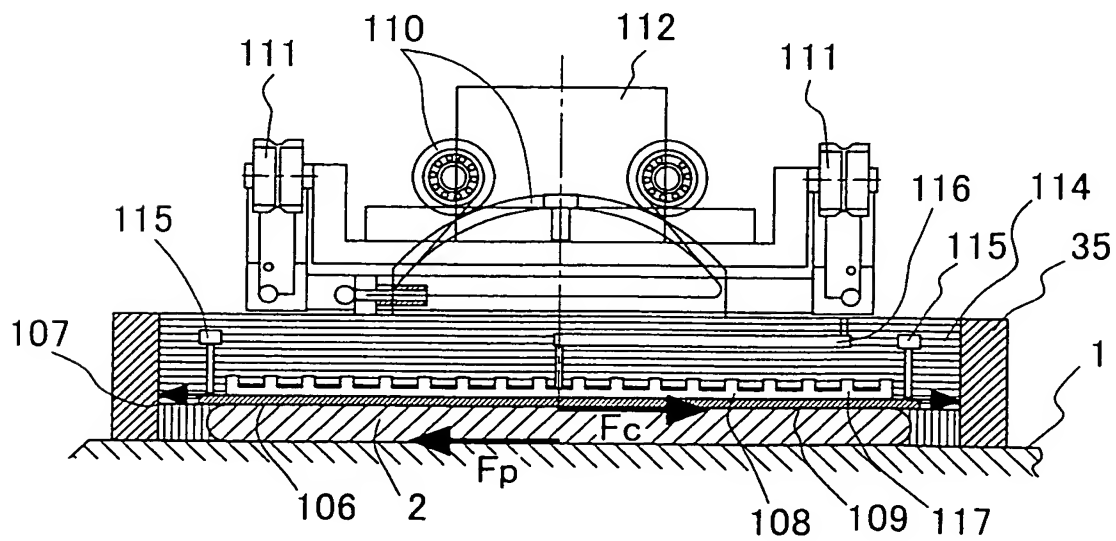


FIG. 7

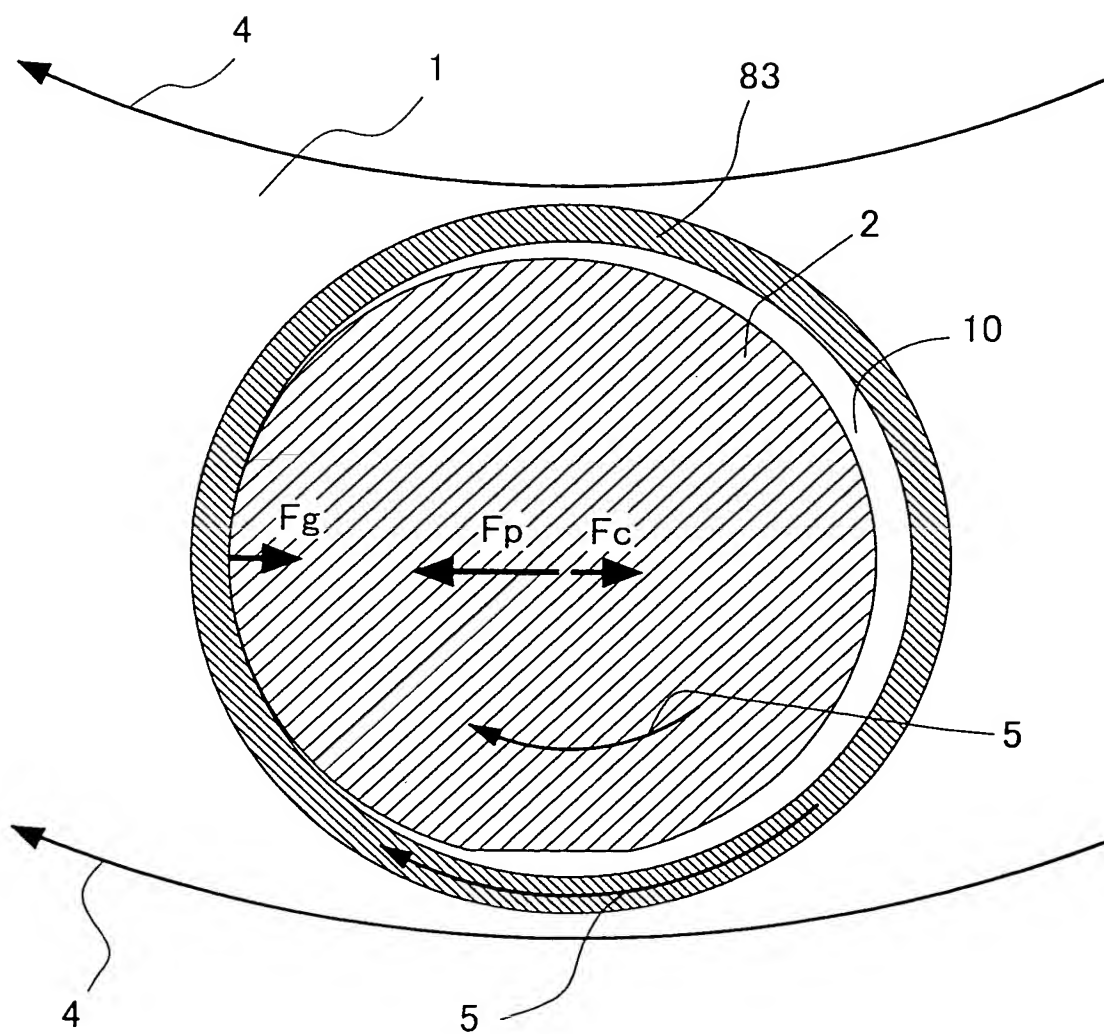


FIG. 8A

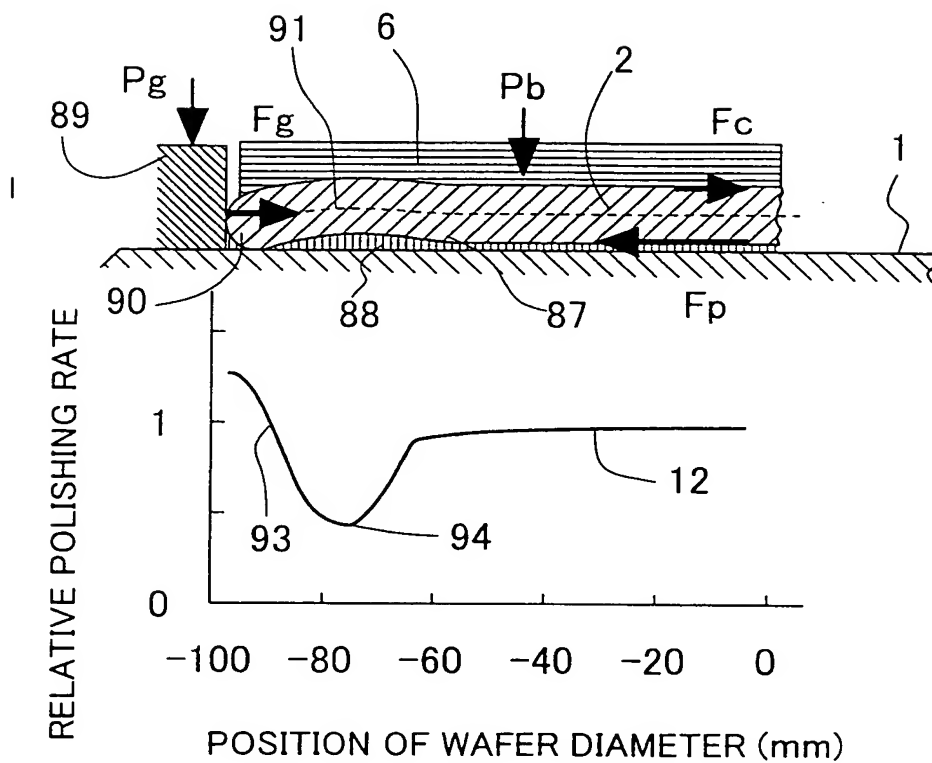


FIG. 8B

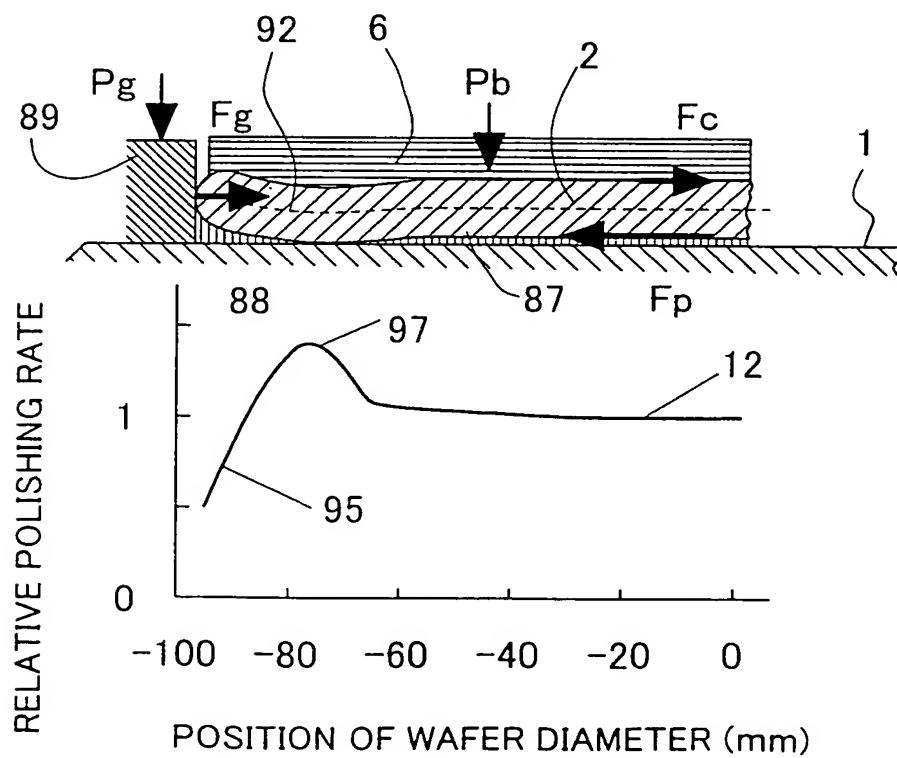


FIG. 9A

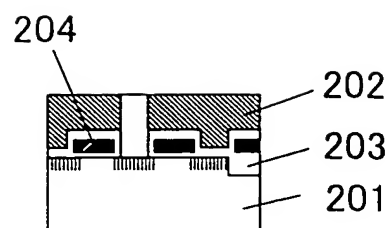
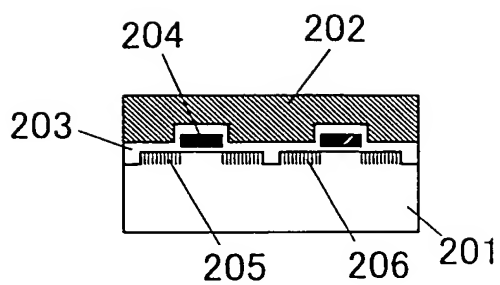


FIG. 9B

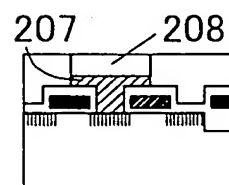
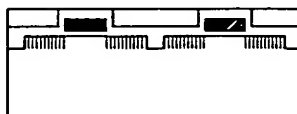


FIG. 9C

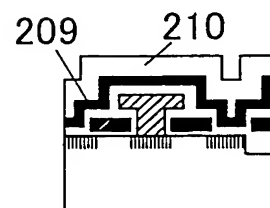
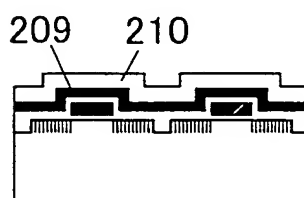


FIG. 9D

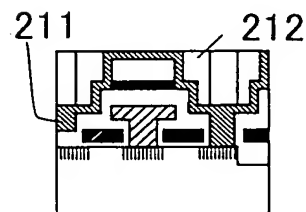
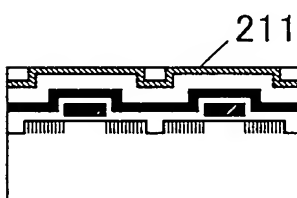


FIG. 9E

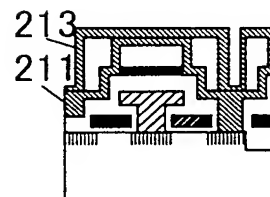
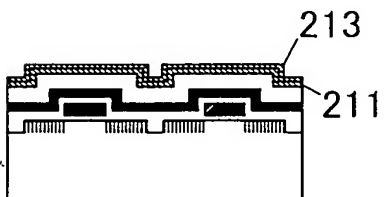


FIG. 9F

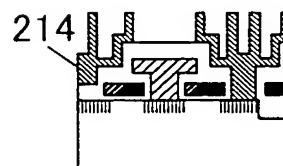
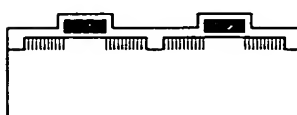


FIG. 9G

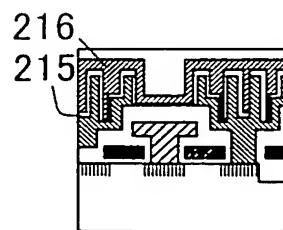
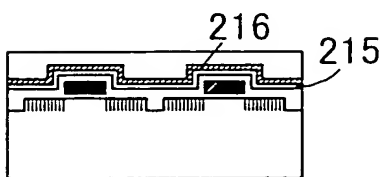


FIG. 10A

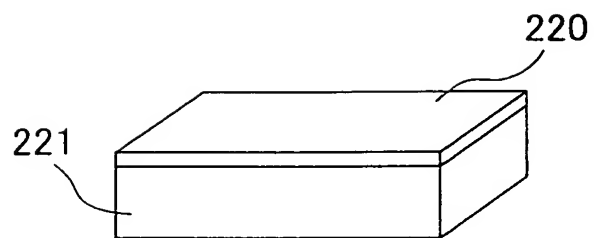


FIG. 10B

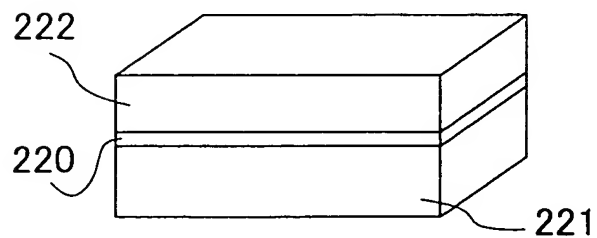


FIG. 10C

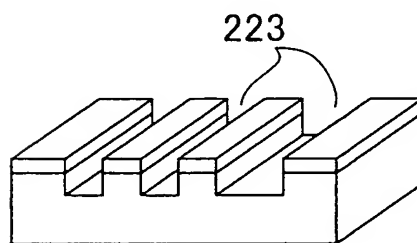


FIG. 10D

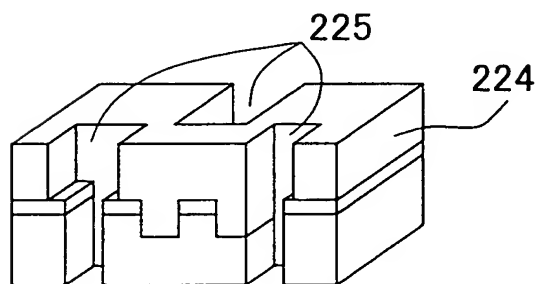


FIG. 10E

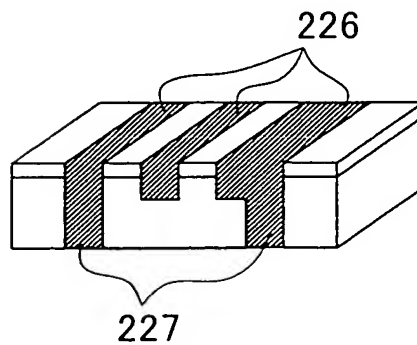


FIG. 11A

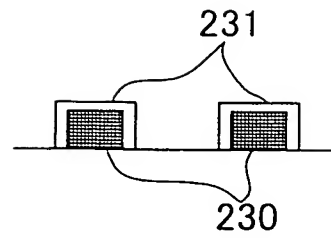


FIG. 11B

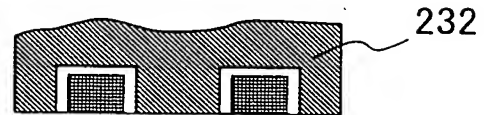


FIG. 11C

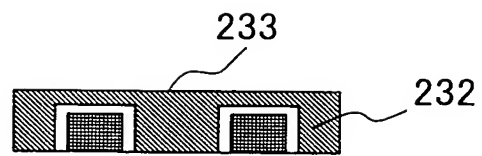


FIG. 11D

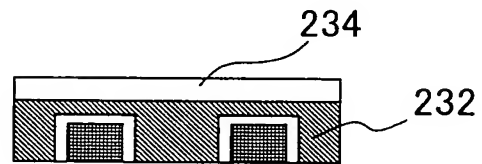


FIG. 11E

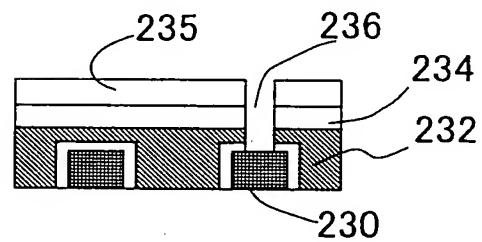


FIG. 11F

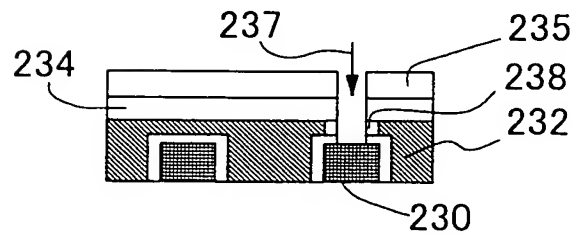


FIG. 11G

